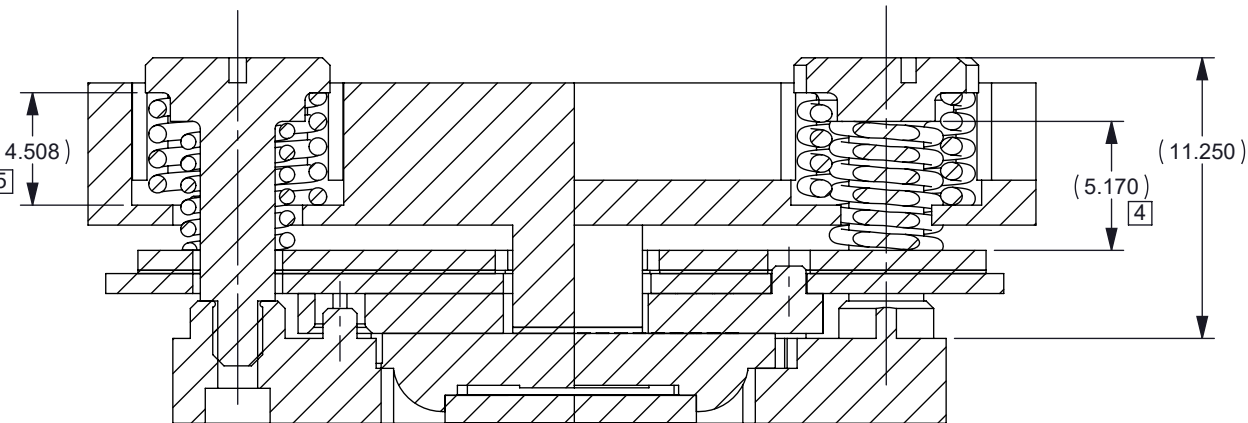


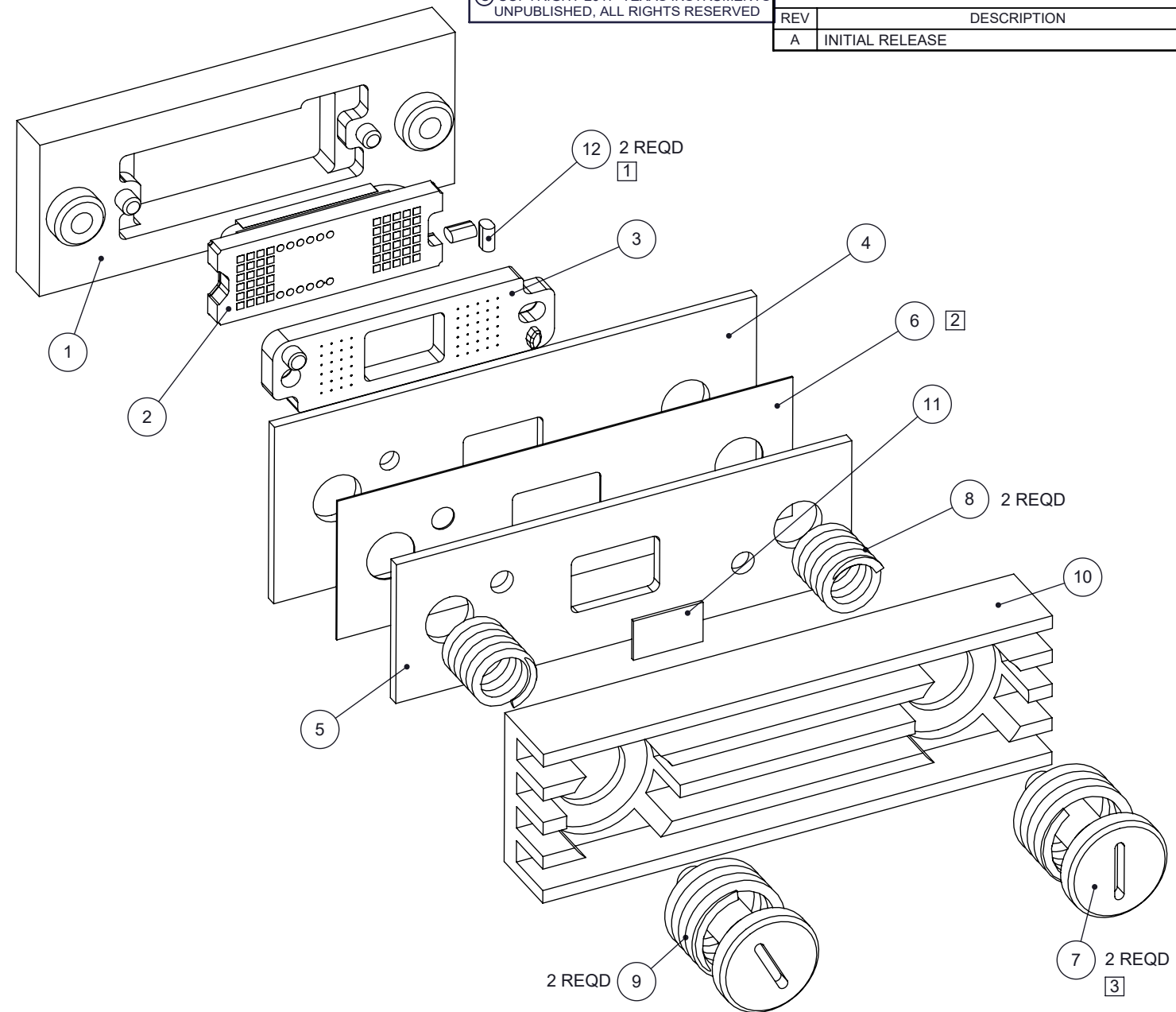
1 THE DMD (ITEM 2) SHOULD BE ALIGNED TO DATUMS 'B' AND 'C' AS SHOWN IN VIEW A. THE FOAM ALIGNMENT SHIMS (ITEM 12) ARE TO BE INSERTED BETWEEN THE DMD EDGES AND THE OPTICAL INTERFACE AT THE APPROXIMATE LOCATIONS SHOWN. THE FUNCTION OF THE ELASTOMERIC WEDGES IS TO HOLD THE DMD AGAINST DATUMS 'B' AND 'C' AFTER IT HAS BEEN MANUALLY POSITIONED. THIS HOLDS THE DMD IN POSITION WHILE THE REMAINING ASSEMBLY IS COMPLETED

3 WHEN TIGHTENING SCREWS (ITEM 7) BE SURE CLAMPING FORCES DO NOT EXCEED THE MAXIMUM LOADS FOR THE THERMAL AND ELECTRICAL INTERFACE AREAS SPECIFIED IN THE DMD DATA SHEET. CARE SHOULD BE TAKEN AS THE SCREWS ARE TIGHTENED TO MAINTAIN A UNIFORM LOAD ACROSS THE AREAS.


5 CRITICAL GAP FOR COIL SPRING DESIGN TO CONTROL LOADS ON THE DMD THERMAL INTERFACE AREA. THE SIZE OF THE GAP WILL VARY DEPENDING ON PART TOLERANCES AND SPRING PROPERTIES.



SECTION B-B



2	12	2512939	SHIM, FOAM ALIGNMENT	
1	11	2515735	THERMAL PAD	
1	10	2515734	HEAT SINK, SERIES 246	
2	9	LEE SPRING LC 028CE 02S	COIL SPRING, THERMAL	
2	8	LEE SPRING LC 024B 02S	COIL SPRING, ELECTRICAL	
2	7	2515739	SCREW, SHOULDER, CONCEPT #1	
1	6	2515738	INSULATOR, PCB, SERIES 246 PCB	
1	5	2515736	CLAMP, SERIES 246	
1	4	2515737	PCB, OUTLINE SERIES 246	
1	3	2515731	INTERPOSER, 54 CONTACT, SERIES 246	
1	2		.23 SERIES 246 DMD	
1	1	2515733	INTERFACE, SERIES 246 DMD MOUNTING CONCEPT 1	
QTY	ITEM	PART NUMBER	DESCRIPTION	Notes

		<div>UNLESS OTHERWISE SPECIFIED</div> <ul style="list-style-type: none">DIMENSIONS ARE IN MILLIMETERSTOLERANCES: ANGLES ±1° 2 PLACE DECIMALS ±0.25 1 PLACE DECIMALS ±0.50DIMENSIONAL LIMITS APPLY BEFORE PROCESSESINTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5M-1994REMOVE ALL BURRS AND SHARP EDGESPARENTHETICAL INFO FOR REF ONLY	DWN J. McKINLEY	DATE 11/5/2017	<div><div>TEXAS INSTRUMENTS</div><div>ASSEMBLY, SERIES 246 MOUNTING CONCEPT</div></div>				
			Engr	CQE/QA	CM				
	0314RD					SIZE B		DWG NO 2515732	REV A
NEXT ASSY	USED ON			Apprvd McKINLEY	11/7/2017	SCALE 1:1		SHEET 1 OF 2	
APPLICATION									

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SSZZ031 January 01, 2013



DWN	DATE
J. McKINLEY	11/5/2017

DATE
11/5/2017

SIZE	B
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DRAWING NO

2515732-Mount-Concept-~~S~~246

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SCALE 2:1

SHEET 2 OF 2